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# Vishay Roederstein

# High Voltage Ceramic Capacitors Radial-Leaded Singlelayer Disc



#### **ADDITIONAL RESOURCES**



QUICK REFERENCE DATA						
DESCRIPTION	VALUE					
Ceramic class	2	2				
Ceramic dielectric	Ye	SP .				
Temperature coefficient of capacitance	± 10 % within -30 °C to +105 °C					
Voltage (U <sub>rated, DC</sub> )	10 000	15 000				
Min. capacitance (pF)	100	100				
Max. capacitance (pF)	2000	2000				
Capacitance tolerance	± 20 %					
Max. dissipation factor (%)	1.5					
Min. insulation resistance (GΩ)	200					
Operating temperature (°C)	-30 to	+105				
Mounting	Rac	dial				

#### RATED VOLTAGE

 $\begin{array}{l} U_{rated,\;AC} = U_{rated,\;DC}/2.8 \; at\; 50\; Hz\; /\; 60\; Hz \\ U_{rated,\;DC} : 10\; 000\; V \rightarrow U_{rated,\;AC} : 3500\; V \\ U_{rated,\;DC} : 15\; 000\; V \rightarrow U_{rated,\;AC} : 5300\; V \end{array}$ 

#### **INSULATION RESISTANCE**

Min. 200 000 M $\Omega$  at 500 V<sub>DC</sub> / 60 s max.

### **TOLERANCE ON CAPACITANCE**

± 20 %

#### **DISSIPATION FACTOR**

Max. 1.5 %

#### **OPERATING TEMPERATURE RANGE**

-30 °C to +105 °C

#### **FEATURES**





RoHS

- · High reliability
- High capacitance values up to 2 nF
- Small sizes
- Low losses
- Radial leads
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### **OPTIONS** (on request)

- ± 10 % tolerance on nominal C-value
- Customized lead styles

#### **APPLICATIONS**

High voltage power supplies for x-ray sources and pulsed lasers

- Baggage scanner
- Medical x-ray
- Industrial laser

#### **DESIGN**

The capacitors consist of a ceramic disc of which both sides are silver-plated. Connection leads are made of tinned copper clad steel wire having diameters of 0.026" (0.65 mm) and 0.032" (0.80 mm).

The capacitors may be supplied with inline and straight leads having lead spacing of 0.37" (9.5 mm) and 0.49" (12.5 mm).

Coating is made of flame retardant epoxy resin in accordance with "UL 94 V-0".

#### **CAPACITANCE RANGE**

100 pF to 2000 pF

### **DIELECTRIC STRENGTH BETWEEN LEADS**

1.5 x U<sub>rated, DC</sub> for maximum 60 s

Test voltage: customer re-test 1.35 x  $U_{\text{rated, DC}}$  for maximum 60 s

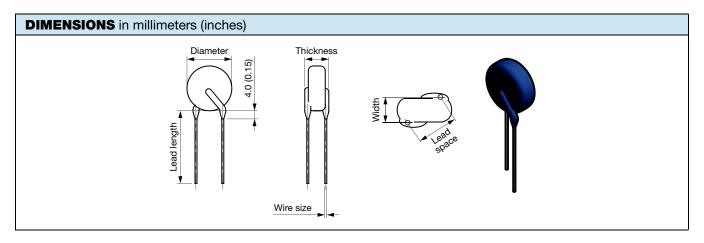
#### Note

- · Considered as destructive test in insulation liquid
- · Avoid flashover between wires and currents higher than 50 mA

#### **CERAMIC DIELECTRIC**

Y6P (± 10 % within -30 °C to +105 °C)





ORD	ORDERING INFORMATION, CERAMIC 10 kV <sub>DC</sub>													
C (pF)	TOL. (%)				MAXIMUM THICKNESS		± 1 mm ± 0		± 0.05 mm ± 5		± 5 mm (± 0.2")		OTH 5 mm .02")	ORDERING CODE
		mm	INCH	mm	INCH	mm	INCH	mm	INCH	mm	INCH	mm	INCH	
100		8	0.31	8.2	0.32							5.3	0.21	HVCC103Y6P101####
150		8	0.31	8	0.31							4.5	0.18	HVCC103Y6P151####
220		9	0.35	0	0.01	12.5		0.80	80 0.032		-	4.5	0.18	HVCC103Y6P221####
330		10	0.39				0.49					4.3	0.17	HVCC103Y6P331####
470	± 20	12	0.47			and	and	and	and	30	1.18	4.3	0.17	HVCC103Y6P471####
680		13	0.51	7.5	0.30	9.5	0.37	0.65	0.026			3.8	0.15	HVCC103Y6P681####
1000		15	0.59	1.5	0.30							3.8	0.15	HVCC103Y6P102####
1500		17	0.67									3.8	0.15	HVCC103Y6P152####
2000		19	0.75									3.8	0.15	HVCC103Y6P202####

ORD	ORDERING INFORMATION, CERAMIC 15 kV <sub>DC</sub>														
C (pF)	TOL. (%)						LEAD SPACE ± 1 mm (± 0.04")		WIRE SIZE ± 0.05 mm (± 0.002") <sup>(1)</sup>		± 5 mm (± 0.2")		WIDTH ± 0.5 mm (± 0.02")		ORDERING CODE
		mm	INCH	mm	INCH	mm	INCH	mm	INCH	mm	INCH	mm	INCH		
100		8	0.31	8.2	0.32							5.3	0.21	HVCC153Y6P101####	
150		8	0.31									4.5	0.18	HVCC153Y6P151####	
220		9	0.35			and an	and a		0.80 0.032 and and 0.65 0.026	30	1.18	4.5	0.18	HVCC153Y6P221####	
330		10	0.39		0.04			and				4.3	0.17	HVCC153Y6P331####	
470	± 20	12	0.47	8								4.3	0.17	HVCC153Y6P471####	
680		13	0.51	0	0.31		0.37	0.65				4.3	0.17	HVCC153Y6P681####	
1000		15	0.59									4.3	0.17	HVCC153Y6P102####	
1500		19	0.75									4.3	0.17	HVCC153Y6P152####	
2000		19	0.75								•	4.3	0.17	HVCC153Y6P202####	

#### Notes

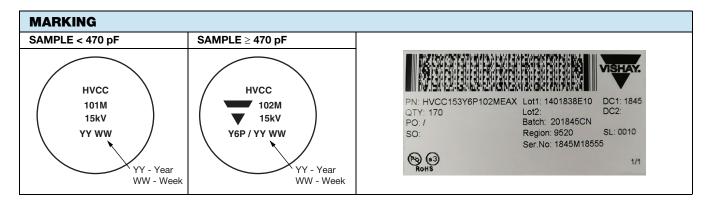
• 20 kV, customized lead styles, and  $\pm$  10 % tolerance are available upon request

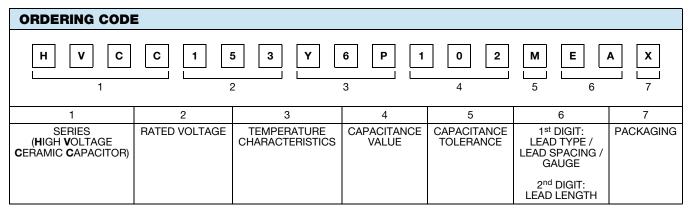
<sup>(1) #20</sup> AWG = 0.8 mm #22 AWG = 0.6 mm



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### **LEAD TYPE** (position 6)

STANDA	STANDARD TYPE									
CODE	LEAD TYPE	LEAD SPACING (mm)	LEAD DIAMETER (mm)	# GAUGE	MATERIAL	LEAD LENGTH (mm)				
AA	Straight LL	9.5 ± 1.0	0.80	20	TCCSW	30 ± 5				
CA	Straight LL	9.5 ± 1.0	0.65	22	TCCSW	30 ± 5				
EA	Straight LL	12.5 ± 1.0	0.80	20	TCCSW	$30 \pm 5$				
GA	Straight LL	12.5 ± 1.0	0.65	22	TCCSW	30 ± 5				

#### Notes

- 1<sup>th</sup> digit: lead type / lead spacing / gauge 2<sup>nd</sup> digit: A = long leads
- LL = long leads
- TCCSW = tinned copper clad steel wire

PACKAGING (position 7)					
CODE	VERSION				
X	Bulk				

PE	PERFORMANCE							
NO.	NO. PARAMETER	SPECIFICATION						
NO.	PARAMETER	TEST CONDITIONS	METHOD AND NOTES					
1	Capacitance	Tol. K = ± 10 % at 1000 h Tol. M = ± 20 % at 1000 h	Components are measured with a LCR-meter. Consider aging of ceramic. Given tolerance is valid 1000 h $\pm$ 24 h after last					
2	Dissipation factor	DF / tan $\delta$ = max. 1.5 %	heating. Before and after that moment, aging offset has to be considered. (See general information for further instructions)					
3	Insulation resistance	$I_R$ = min. 200 GΩ in 60 s t = 5 s U = 500 V <sub>DC</sub> ± 10 V <sub>DC</sub>	NOTE: very high resistances are sensitive to the surrounding area may lead to unstable measurement values					



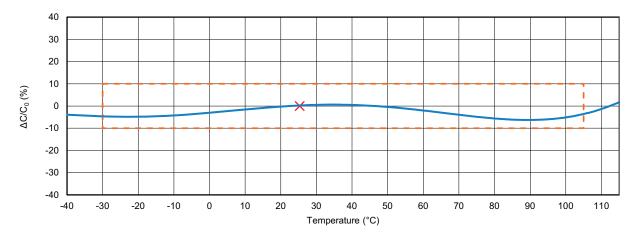
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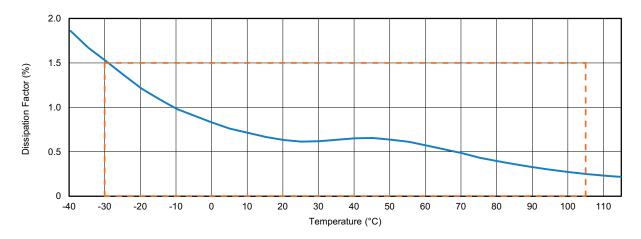
PE	RFORMANCE		ODEOLEIOATION		
NO.	PARAMETER	TEGT GOLDITIONS	SPECIFICATION		
4	Dielectric strength (between lead wires)	TEST CONDITIONS  U1 = +1.35 x $U_{RDC}/U_{RAC}$ max. 60 s U2 = -1.35 x $U_{RDC}/U_{RAC}$ max. 60 s $t_{U1} = t_{U2} = 60$ s $t_{max.} = 50$ mA	METHOD AND NOTES  1. Apply +1.35 x U <sub>RDC</sub> /U <sub>RAC</sub> for max. 60 s 2. Unload part (I <sub>max.</sub> = 50 mA) 3. Apply -1.35 x U <sub>RDC</sub> for max. 60 s 4. Unload part (I <sub>max.</sub> = 50 mA) 5. Avoid current spikes higher than 50 mA		
5	Appearance and marking	No visible damage. The marking shall be legible	Visual inspection		
6	Dimensions	Dimensions are within specification	Measurement by caliper gauge		
7.1	Temperature characteristics / TCC	EIA code = Y6P $\Delta$ C/C <sub>0</sub> = ± 10 % Temp. range = -30 °C to 105 °C	Measurement is done from cooler temperatures to hotter temperatures in reasonable temperature steps. Other way		
7.2	Temperature characteristics / TCDF	DF / $\tan \delta = \max$ . 1.5 % Temp. range = 20 °C to 105 °C	round you get have to consider deaging effects.		
8	Dielectric strength of body insulation	U = 5000 V <sub>DC</sub> t = 60 s	1. Connect both lead wires together 2. Dip component headfirst into a bath with oil and metal balls (fig.) 3. Apply voltage between lead wires and metal balls  Metal foil About 3 mm to 4 mm  Metal Metal Metal Metal balls		
9	Pulse test	$t_r$ = 1.2 μs $t_f$ = 50 μs $U$ = 1.25 x $U_{RDC}$ $n$ = 50 x single polarity	Rise time: $t_s = 1.2 \ \mu \text{s} \pm 30 \ \%$ Half value time: $t_{\gamma} = 50 \ \mu \text{s} \pm 20 \ \%$ Over swing: $\ddot{u} < 5 \ \%$		
10	Life test	U = 1.25 x U <sub>RDC</sub> t = min. 1000 h T = max. 105 °C I <sub>max.</sub> = 50 mA	1. Initial measurement including no. 1, 2, 3, and 8 2. Condition the components to test temperature 3. Carry out life test / avoid 0 $\Omega$ short circuit 4. Final measurement including no. 1, 2, 3, and 8 Result: voltage breakdowns are not accepted		
11	Steady state test (without load)	T = 40 °C RH = 93 % t = 240 h / 10 days U = 1.5 x U <sub>RDC</sub>	1. Initial measurement including no. 1, 2, 3, and 8     2. Carry out steady state test     3. Final measurement including no. 1, 2, 3, and 8     Result: voltage breakdowns are not accepted		
12	Temperature cycle	$T_{LOW} = -40 ^{\circ}\text{C}$ $T_{HIGH} = +105 ^{\circ}\text{C}$ $t_{DWELL} = 1800 \text{s}$ $t_{CHANGE} = about 300 \text{s}$ $n = 50 \text{x}$	1. Initial measurement including no. 1, 2, 3, and 8     2. Carry out temperature cycle     3. Final measurement including no. 1, 2, 3, and 8     Result: voltage breakdowns and cracks in coating are not accepted		
13	Solderability	T <sub>SOLDER</sub> = max. 250 °C t = max. 3 s dist. solder-epoxy = min. 2 mm	1. Initial measurement incl. no. 1, 2, 3, and 8 2. Carry out test (solder material: no known restrictions) 3. Final measurement incl. 1, 2, 3, and 8 Result: voltage breakdowns are not accepted		
14	Strength of lead wire / pulling	F <sub>PULL</sub> = max. 10 N t <sub>PULL</sub> = max. 10 s	Fix the body of component, apply a tensile weight gradually each lead wire in the radial direction of capacitor up to 20 N and keep it for 10 s $\pm$ 1 s		
15	Strength of lead wire / bending	F <sub>BEND</sub> = max. 5 N t <sub>BEND</sub> = 2 s to 3 s	Bending each lead wire to 90° from the lead egress with 2.5 force, then back to original position and bent again from th same direction. Totally 3 bends, 3 s each time.  1 bend: bending to 90° the return to normal position is one bend. Start from 1.6 mm to 3.2 mm from the part body		



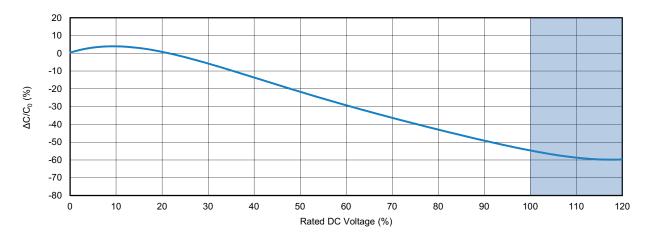
### **TYPICAL TCC Y6P**



### **TYPICAL TCDF Y6P**

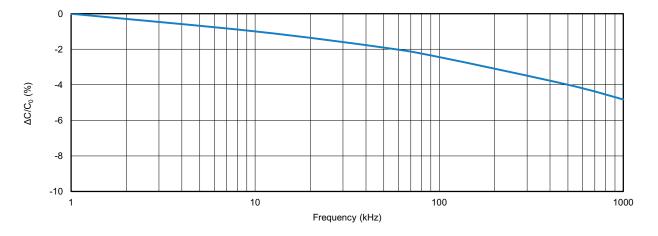


# TYPICAL Y6P - $\Delta$ C/C<sub>0</sub> / % VS. U<sub>rated, DC</sub>

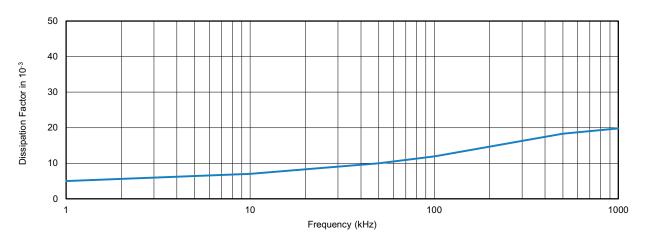




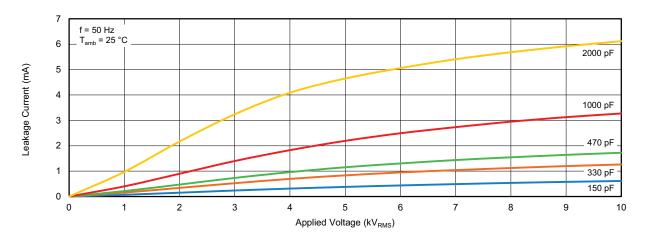
### TYPICAL Y6P - $\triangle$ C/C<sub>0</sub> / % VS. FREQUENCY



#### **TYPICAL Y6P TCDF VS. FREQUENCY**



### TYPICAL Y6P AC CURRENT VS. APPLIED VOLTAGE (LEAKAGE CURRENT)





### 1. QUALIFICATION

#### 1.1 BASICS

All components are tested according to the related testing plan, which you find in series datasheet. The test procedures are more severe than noted in the datasheet due to aging and storage effects of the components. We do not guarantee if any limit is exceeded. Internal test procedures are more severe than noted in the table "Performance" because of aging and storage effects of the components.

#### 1.2 LIMITS OF APPLICATION

Please take care whilst designing our parts into one of these applications, which require highest reliability and possible errors might harm life, body or property of a third party.

- Transportation (aerospace, aircraft, train, ship, submarine, etc.)
- Medical equipment
- Critical control equipment (power plant, traffic signals, disaster prevention)
- Other application requiring similar reliability characteristics

#### 2. STORAGE

#### 2.1 ORIGINAL PACKAGING

Storing in the sealed original packages is preferred.

#### 2.2 STORING CONDITIONS

Epoxy coating does not protect perfectly from all environmental conditions. Some materials can penetrate the epoxy and harm the performance of the parts. Therefore it is not recommended to use or store the parts in corrosive or humid atmosphere.

Optimal storing conditions should not exceed -10 °C to +40 °C and 15 % to 85 % relative humidity. When following these recommendations it is impossible, drying at 150 °C/60 min is recommended before assembly. If following this recommendation is not possible, drying the components at 150 °C/60 min is recommended before assembly.

#### 3. ASSEMBLY

#### 3.1 WIRE FORMING

If wire forming is needed, excessive mechanical force to the component body must be avoided as it might cause cracks in the ceramic element.

Do not crack coating extension of the epoxy layer, when applying force onto the wire.

#### 3.2 SOLDERING

Do not exceed resistance to soldering heat specification of the component. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

#### Manual Soldering / Rework

Set the soldering iron (50 W max.) to less than 400 °C and solder the wires within 4 seconds onto the PCB. Exceeding that recommendations might reduce the electrical performance of the component.

#### **Wave Soldering**

Most common way to assemble these kind of components is carried out in 4 steps:

- 1. Increasing temperature to 120 °C within about 20 s
- 2. Preheating at 120 °C for about 60 s
- 3. Soldering at 260 °C in less than 10 s
- 4. Gradual air cooling in constant air flow

#### **Reflow Soldering**

It is not recommended to use reflow soldering with these components.

#### 3.3 MOLDING AND COATING

Molding and / or applying another coating material might harm the performance of the components. Therefore it is recommended to test the electrical characteristics of the molded / coated part in advance.

Typical error is a reduced withstand voltage because of an inadequate solvent in the molding material, which penetrates the epoxy coating. A similar result can be caused by an inadequate coating material, which might pull the original epoxy off the ceramic element.



#### 4. CLEANING AND DRYING

#### **4.1 CLEANING AGENTS**

Cleaning agents might have an influence to the performance of the components after washing and after unsuitable drying. The following agents have been tested and classified:

**Not Recommended** 

Acetone

#### Recommended

- DI water
- Isopropanol
- Ethanol
- · Ehtyl alcohol
- ..

#### **4.2 ULTRASONIC**

Settings for ultrasonic cleaning

Rinse bath capacity: output of 20 Watts per liter or less

Rinsing time: 5 min max.

Do not vibrate the PCB / PWB directly.

Excessive ultrasonic cleaning may lead to permanent destruction of the component.

#### 4.3 DRYING

It is recommended to dry the assembled PCB (washed components) for 1 hour at a temperature of 20 °C higher than the boiling point of the used cleaning agent. Exceeding 150 °C permanently should be avoided.

#### 5. TESTING AND OPERATION

#### **5.1 SHORT CIRCUIT**

Avoid repetitive zero-ohm-short circuits because they might harm the components core construction, such as arcs between lead wires because of inadequate insulation material (e.g air).

#### **5.2 INSULATION**

During operation, components should be surrounded by adequate insulating material (silicone oil, epoxy or molding material). Voltage breakdowns or leakage current through this material (between lead wires or to ground) is not acceptable.

#### **5.3 APPLIED VOLTAGE**

When using DC-rated components in AC applications (also ripple) the peak to peak voltage should not exceed the nominal DC-rating of the component.

#### 6. CAUTION

#### 6.1 OPERATING VOLTAGE AND FREQUENCY CHARACTERISTIC

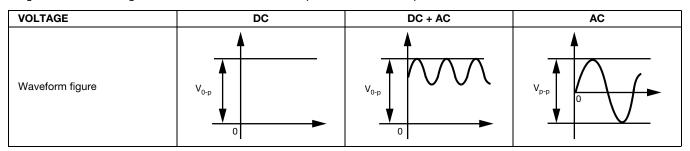
When sinusoidal or ripple voltage applied to DC ceramic disc capacitors, be sure to maintain the peak-to-peak value or the peak value of the sum of both AC + DC within the rated voltage.

When start or stop applying the voltage, resonance may generate irregular voltage.

When rectangular or pulse wave voltage is applied to DC ceramic disc capacitors, the self-heating generated by the capacitor is higher than the sinusoidal application with the same frequency. The allowable voltage rating for the rectangular or pulse wave corresponds approximately with the allowable voltage of a sinusoidal wave with the double fundamental frequency.

The allowable voltage varies, depending on the voltage and the waveform.

Diagrams of the limiting values are available for each capacitor series on request.







### 6.2 OPERATING TEMPERATURE AND SELF-GENERATED HEAT

The surface temperature of the capacitors must not exceed the upper limit of its rated operating temperature.

During operation in a high-frequency circuit or a pulse signal circuit, the capacitor itself generate heat due to dielectric losses.

Applied voltage should be the load such as self-generated heat is within 20 °C on the condition of environmental temperature 25 °C.

Note, that excessive heat may lead to deterioration of the capacitor's characteristics.

RELATED DOCUMENTS					
General Information	www.vishay.com/doc?22001				
Product Sheet	www.vishay.com/doc?48508				
Infographic	www.vishay.com/doc?48450				

SAMPLE KIT	
Part Number	HVCC-KIT-HV
Link	www.vishay.com/doc?23147



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